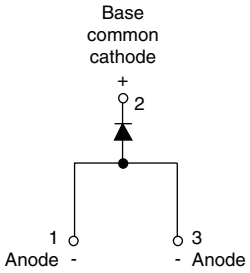
Surface Mount Fast Soft Recovery Rectifier Diode, 8 A

D-PAK



FEATURES

- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

Pb
e3
RoHS COMPLIANT

APPLICATIONS

- Output rectification and freewheeling diode in inverters, choppers and converters
- Input rectifications where severe restrictions on conducted EMI should be met

DESCRIPTION

The VS-8EWF..S-M3 fast soft recovery rectifier series has been optimized for combined short reverse recovery time, low forward voltage drop and low leakage current.

The glass passivation ensures stable reliable operation in the most severe temperature and power cycling conditions.

PRODUCT SUMMARY	
Package	D-PAK (TO-252AA)
$I_{F(AV)}$	8 A
V_R	1000 V, 1200 V
V_F at I_F	1.3 V
I_{FSM}	150 A
t_{rr}	80 ns
T_J max.	150 °C
Diode variation	Single die
Snap factor	0.6

MAJOR RATINGS AND CHARACTERISTICS			
SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Sinusoidal waveform	8	A
V_{RRM}		1000/1200	V
I_{FSM}		150	A
V_F	8 A, T_J = 25 °C	1.3	V
t_{rr}	1 A, 100 A/µs	80	ns
T_J	Range	- 40 to 150	°C

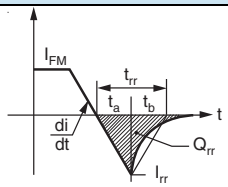
VOLTAGE RATINGS			
PART NUMBER	V_{RRM}, MAXIMUM PEAK REVERSE VOLTAGE V	V_{RSM}, MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM} AT 150 °C mA
8EWF10SPbF	1000	1100	4
8EWF12SPbF	1200	1300	

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	T_C = 94 °C, 180° conduction half sine wave	8	A
Maximum peak one cycle non-repetitive surge current	I_{FSM}	10 ms sine pulse, rated V_{RRM} applied	125	
		10 ms sine pulse, no voltage reapplied	150	
Maximum I^2t for fusing	I^2t	10 ms sine pulse, rated V_{RRM} applied	78	A^2s
		10 ms sine pulse, no voltage reapplied	110	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	t = 0.1 to 10 ms, no voltage reapplied	1100	$A^2\sqrt{s}$

ELECTRICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop	V_{FM}	8 A, T_J = 25 °C		1.3	V
Forward slope resistance	r_t	T_J = 150 °C		25.6	mΩ
Threshold voltage	$V_{F(TO)}$			0.93	V
Maximum reverse leakage current	I_{RM}	T_J = 25 °C	V_R = Rated V_{RRM}	0.1	mA
		T_J = 150 °C		4	

RECOVERY CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Reverse recovery time	t_{rr}	I_F at 8 A_{pk} 25 A/µs T_J = 25 °C	270	ns	
Reverse recovery current	I_{rr}		4.2	A	
Reverse recovery charge	Q_{rr}		1	µC	
Snap factor	S		0.6		

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		- 40 to 150	°C
Maximum thermal resistance, junction to case	R_{thJC}	DC operation	2.5	°C/W
Typical thermal resistance, junction to ambient (PCB mount)	R_{thJA} (1)		50	
Soldering temperature	T_S	For 10 seconds	260	°C
Approximate weight			1	g
			0.03	oz.
Marking device		Case style D-PAK (TO-252AA)	8EWF12S	

Note

(1) When mounted on 1" square (650 mm^2) PCB of FR-4 or G-10 material 4 oz. (140 µm) copper 40 °C/W
For recommended footprint and soldering techniques refer to application note #AN-994

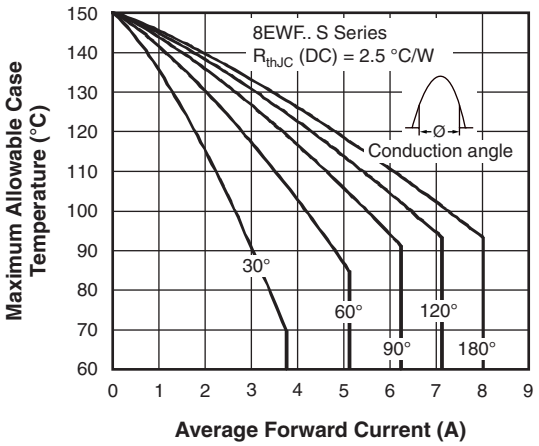


Fig. 1 - Current Rating Characteristics

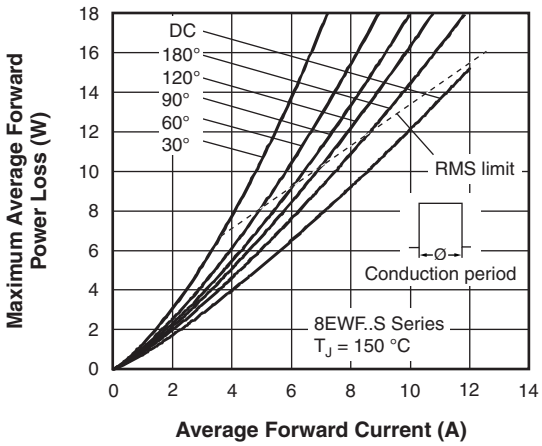


Fig. 4 - Forward Power Loss Characteristics

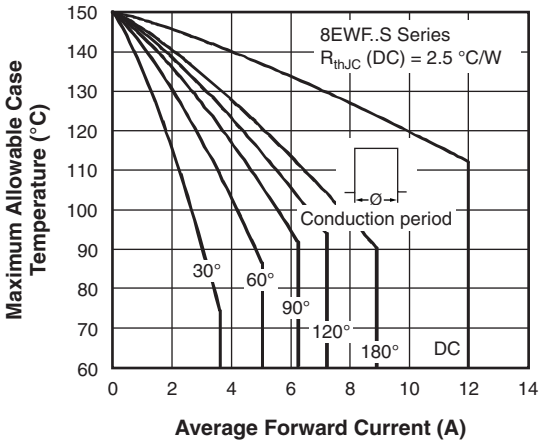


Fig. 2 - Current Rating Characteristics

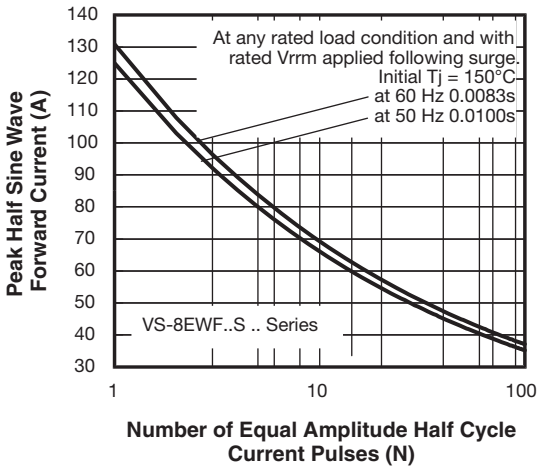


Fig. 5 - Maximum Non-Repetitive Surge Current

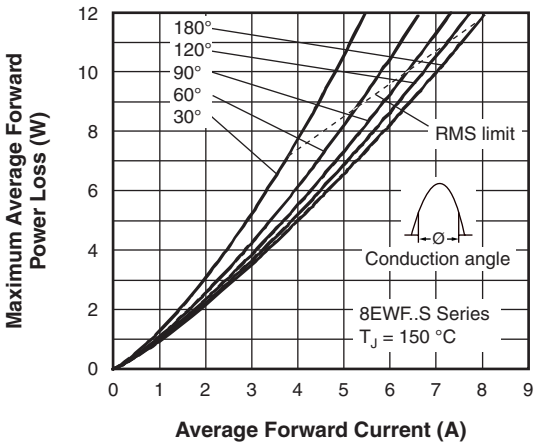


Fig. 3 - Forward Power Loss Characteristics

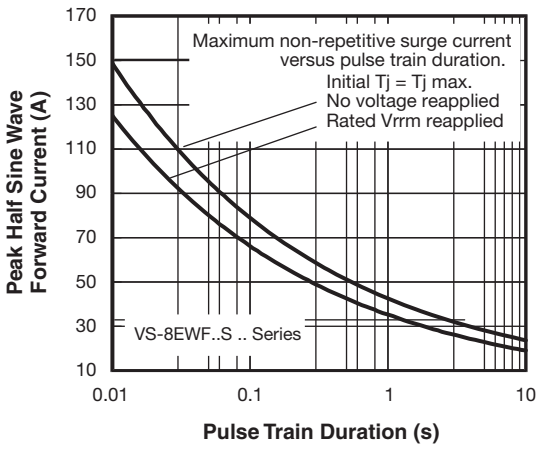


Fig. 6 - Maximum Non-Repetitive Surge Current

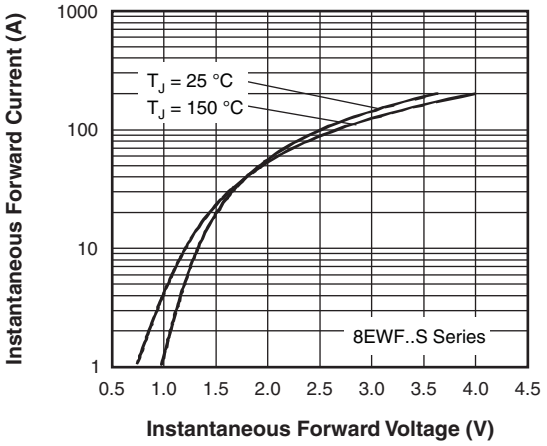


Fig. 7 - Forward Voltage Drop Characteristics

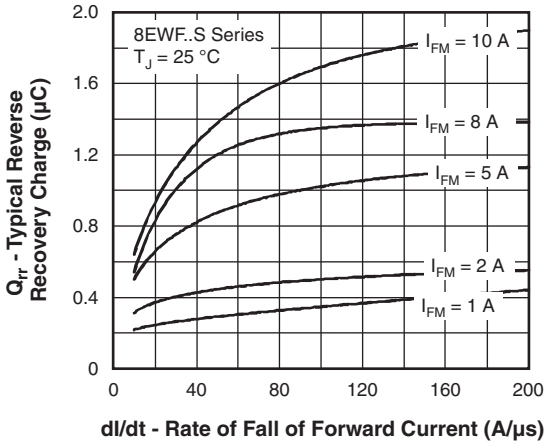


Fig. 10 - Recovery Charge Characteristics, T_J = 25 °C

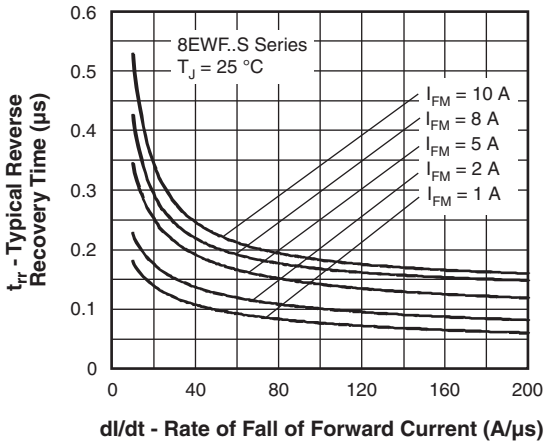


Fig. 8 - Recovery Time Characteristics, T_J = 25 °C

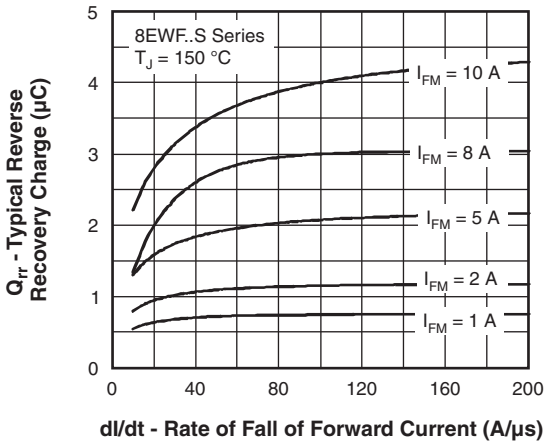


Fig. 11 - Recovery Charge Characteristics, T_J = 150 °C

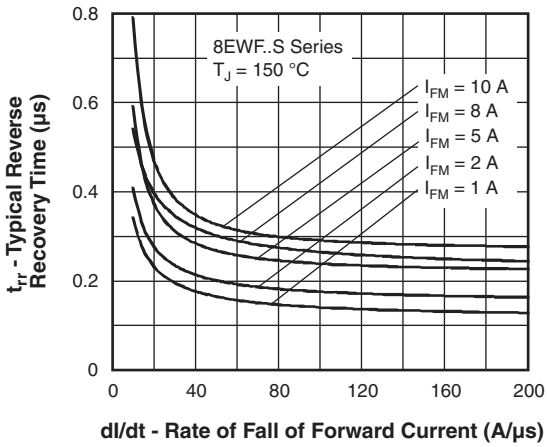


Fig. 9 - Recovery Time Characteristics, T_J = 150 °C

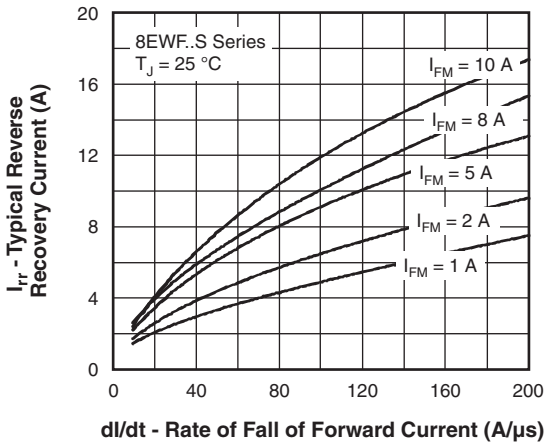


Fig. 12 - Recovery Current Characteristics, T_J = 25 °C

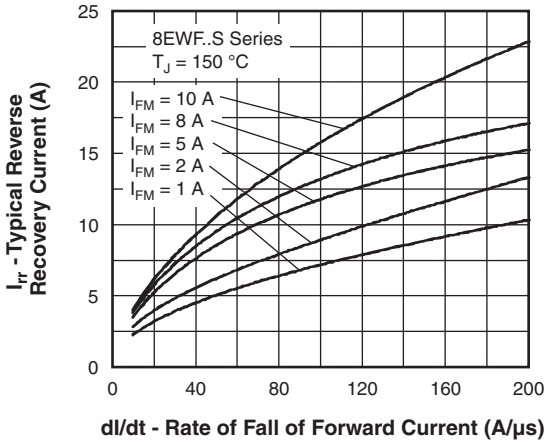


Fig. 13 - Recovery Current Characteristics, T_J = 150 °C

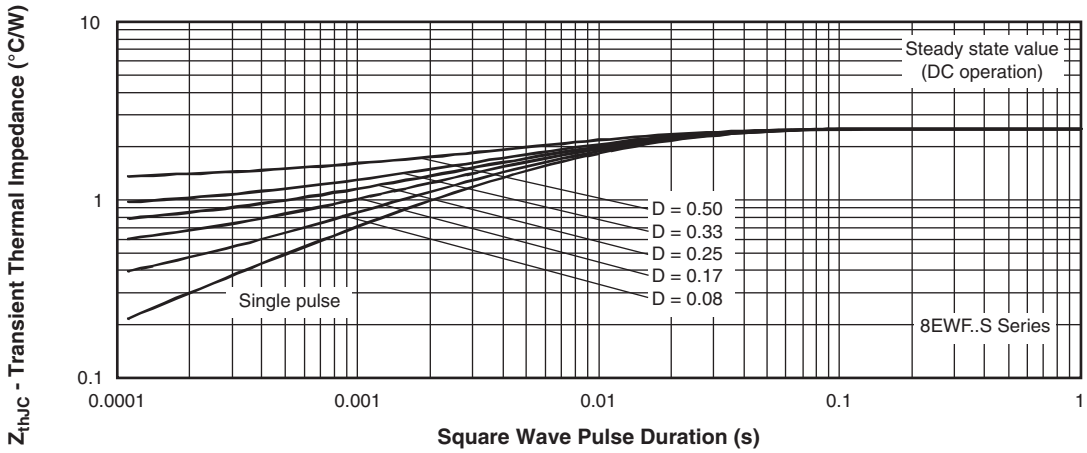
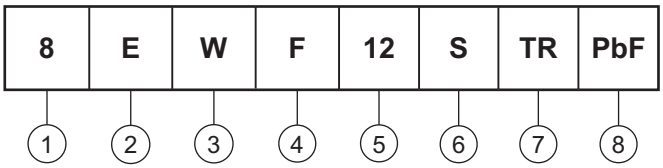


Fig. 14 - Thermal Impedance Z_{thJC} Characteristics

ORDERING INFORMATION TABLE

Device code



1 - Current rating (8 = 8 A)

2 - Circuit configuration:
E = Single diode

3 - Package:
W = D-PAK

4 - Type of silicon:
F = Fast soft recovery rectifier

5 - Voltage code x 100 = V_{RRM}
10 = 1000 V
12 = 1200 V

6 - S = Surface mountable

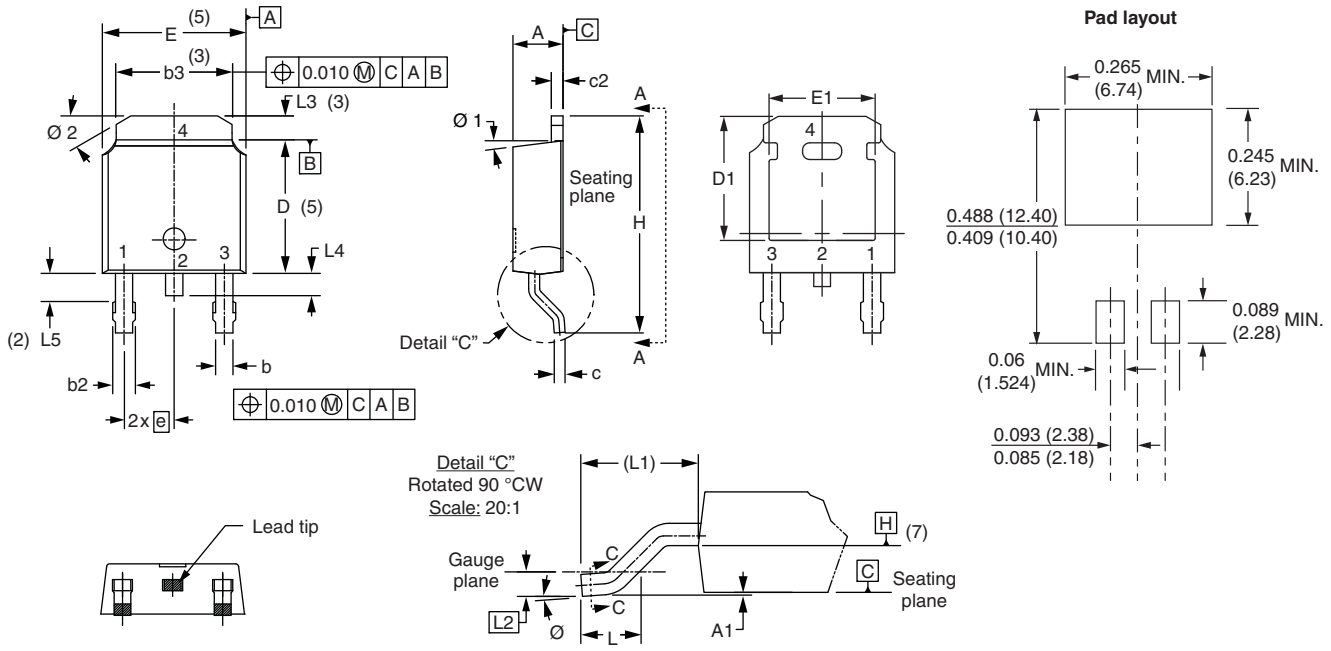
7 - • TR = Tape and reel
• TRR = Tape and reel (right oriented)
• TRL = Tape and reel (left oriented)

8 - • None = Standard production
• PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95016
Part marking information	www.vishay.com/doc?95059
Packaging information	www.vishay.com/doc?95033
SPICE model	www.vishay.com/doc?95552

D-PAK (TO-252AA)

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	0.086	0.094	
A1	-	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
c	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	5.21	-	0.205	-	3
E	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
e	2.29 BSC		0.090 BSC		
H	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74 BSC		0.108 REF.		
L2	0.51 BSC		0.020 BSC		
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2
Ø	0°	10°	0°	10°	
Ø1	0°	15°	0°	15°	
Ø2	25°	35°	25°	35°	

Notes

(1) Dimensioning and tolerancing as per ASME Y14.5M-1994
(2) Lead dimension uncontrolled in L5
(3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
(4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
(5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
(6) Dimension b1 and c1 applied to base metal only
(7) Datum A and B to be determined at datum plane H
(8) Outline conforms to JEDEC outline TO-252AA

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, “Vishay”), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay’s knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer’s responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer’s technical experts. Product specifications do not expand or otherwise modify Vishay’s terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

Material Category Policy

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.